Supplier Name: **Texas Instruments Inc. (DUNS# 00-732-1904)**
Contact Info: ti.com/support
Form/Declaration Type: **Distribute - RoHS and IEC 62474 DB**
Created on: **06/05/2022**

Details for "OPA4830IPW"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package | Pins	Package body size (mm)	Total device mass (mg)*
OPA4830IPW	NIPDAU	Level-2-260C-1 YEAR	TI MALAYSIA A/T	PW | 14	4.4x5x1.15	67.4

***Total Device Mass**
The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

				Homogeneous Material Level		Component Level	
Component	**Substance**	**CAS Number**	**Amount (mg)**	**Percentage %**	**ppm**	**Percentage %**	**ppm**
Bond Wire							
Other Nonferrous Metals and Alloys	Yttrium	7440-65-5	0.000001	0.000666	7	0.000001	0
Precious Metals	Gold	7440-57-5	0.150065	99.998001	999980	0.222634	2226
Precious Metals	Silver	7440-22-4	0.000002	0.001333	13	0.000003	0
Sub-Total			**0.150068**	**100**	**1000000**	**0.222638**	**2226**
Die Attach Adhesive							
Precious Metals	Silver	7440-22-4	0.285982	80.000112	800001	0.424277	4243
Thermoplastics	Epoxy	85954-11-6	0.071495	19.999888	199999	0.106069	1061
Sub-Total			**0.357477**	**100**	**1000000**	**0.530346**	**5303**
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	28.67088	97.52	975200	42.535575	425356
Copper and Its Alloys	Iron	7439-89-6	0.6762	2.3	23000	1.003198	10032
Copper and Its Alloys	Phosphorus	7723-14-0	0.00882	0.03	300	0.013085	131
Zinc and Its Alloys	Zinc	7440-66-6	0.0441	0.15	1500	0.065426	654
Sub-Total			**29.4**	**100**	**1000000**	**43.617284**	**436173**
Lead Frame Plating							
Nickel and Its Alloys	Nickel	7440-02-0	0.113954	95.1202	951202	0.16906	1691
Precious Metals	Gold	7440-57-5	0.000934	0.779633	7796	0.001386	14
Precious Metals	Palladium	7440-05-3	0.004912	4.100167	41002	0.007287	73
Sub-Total			**0.1198**	**100**	**1000000**	**0.177733**	**1777**
Mold Compound							
Other Inorganic Materials	Silica	7631-86-9	30.776081	85	850000	45.658812	456588
Other Plastics and Rubber	Carbon Black	1333-86-4	0.181036	0.500001	5000	0.268582	2686
Thermoplastics	Epoxy	85954-11-6	5.250037	14.499999	145000	7.788856	77889
Sub-Total			**36.207154**	**100**	**1000000**	**53.716249**	**537162**
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	1.169973	100	1000000	1.73575	17357
Sub-Total			**1.169973**	**100**	**1000000**	**1.73575**	**17357**
Total			67.404472			100	1000000

Important Note
The ppm calculations are at the **homogeneous material** level and are maximum concentration values. The ppm displayed represents the **homogeneous material** with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.
The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**.
See Glossary of Terms for more details.

Important Part Information
There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSIs or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology
For an explanation of the methods used to determine material weights, See Product Content Methodology

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

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For additional information, please contact TI customer support.

Signature: (click here for a fuller statement with a signed certificate)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality
For further environmental statements, please go to www.ti.com/ecoinfo
Created on: 06/05/2022

RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in http://www.ti.com/lit/pdf/szzq088

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb203) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.